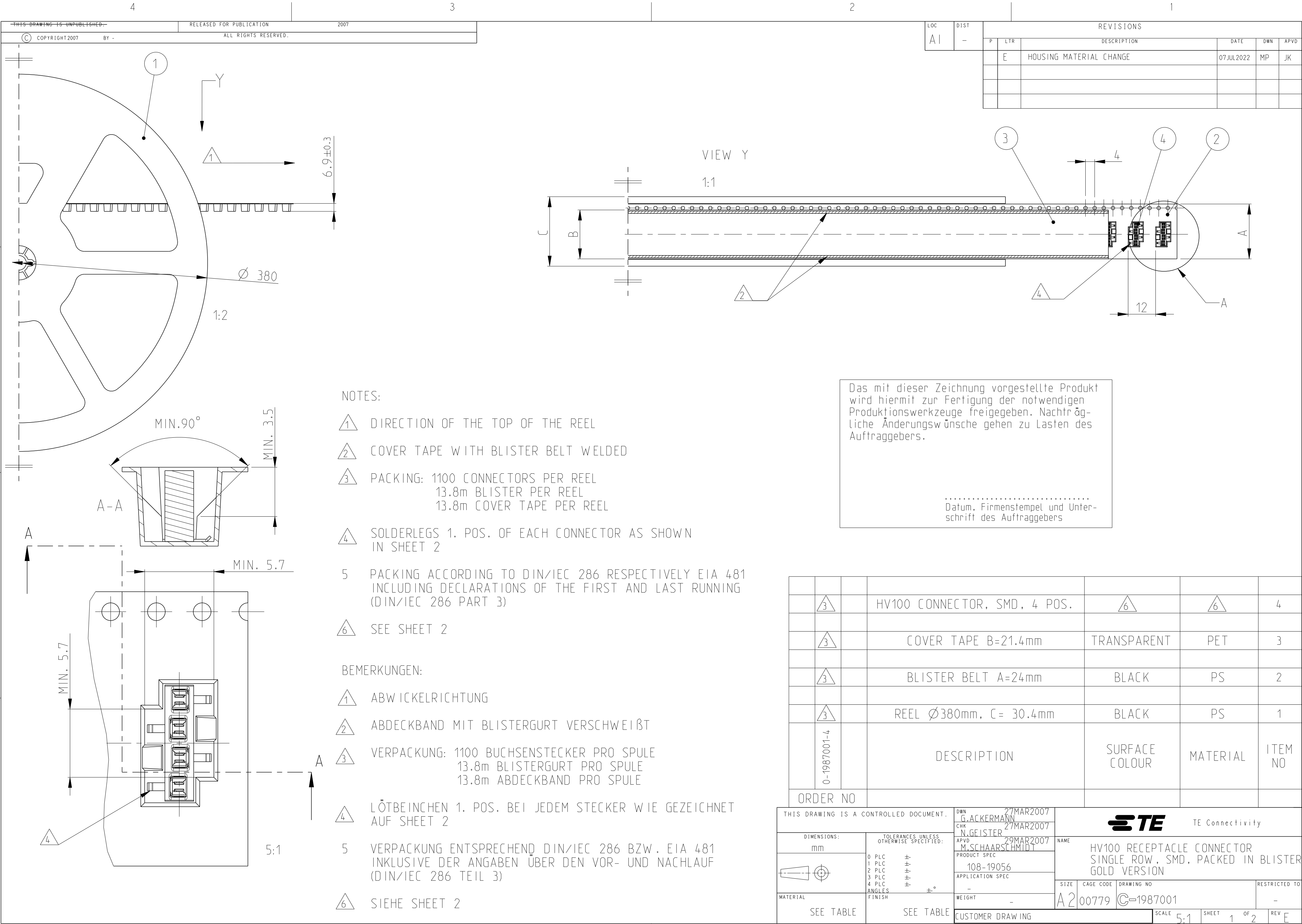
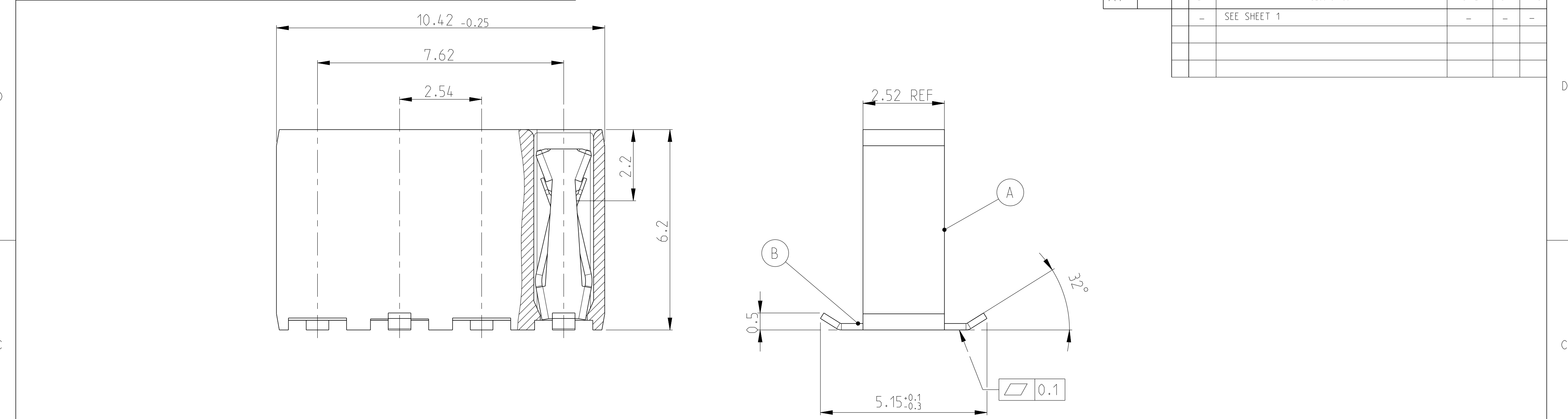






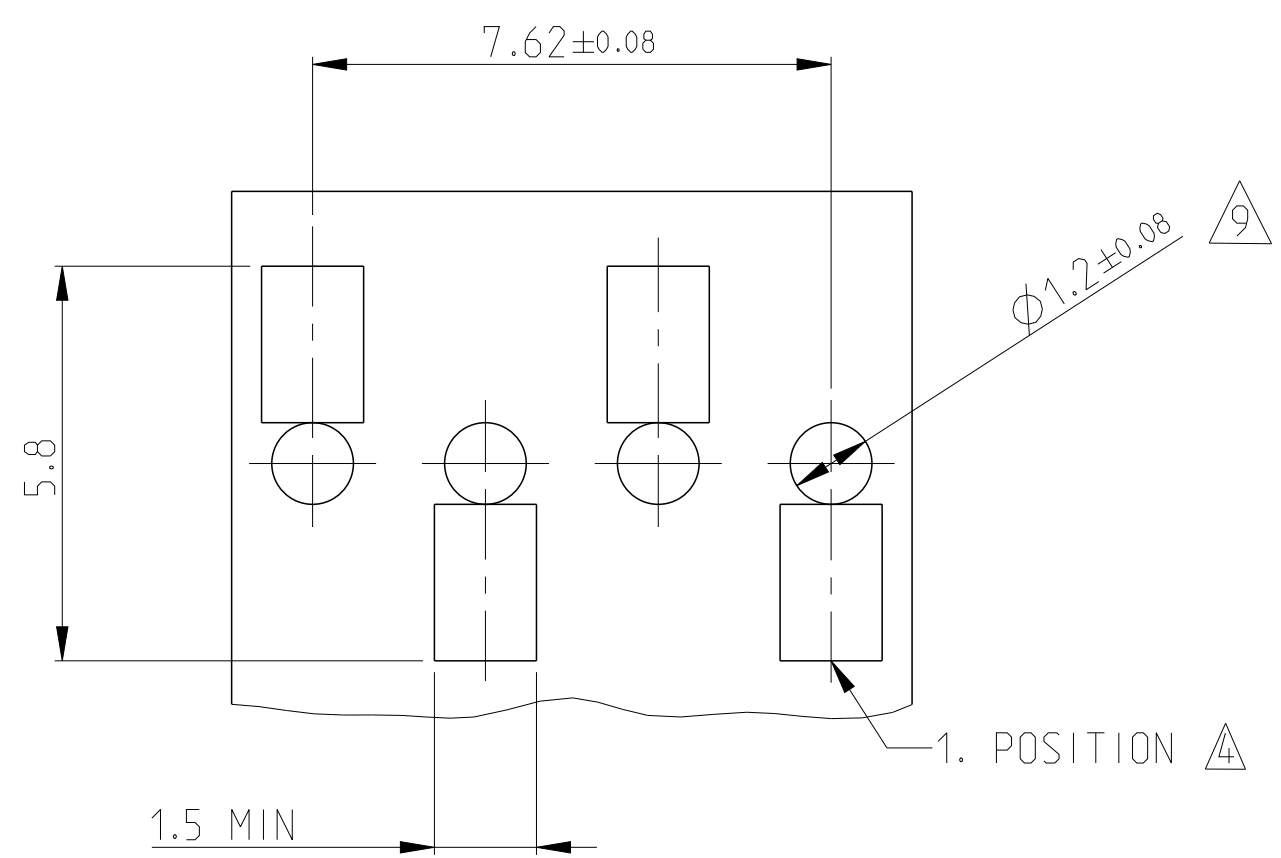
NOTE

CONTACT RANGE: 0.8 μm GOLD OVER 1.3 μm Ni
SOLDERING RANGE: 2.5 μm TIN OVER 1.3 μm Ni

8. CAN BE PLUGGED IN WITH MODU II PINS
Ø0.63 OR □0.63 TOP OR BOTTOM ENTRY

9. ONLY WITH THE BOTTOM ENTRY

Recommended PCB Layout



HV 100 CONTACT	CuSn		B	THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN	27MAR2007		TE Connectivity								
				DIMENSIONS:		CHK	27MAR2007		NAME								
				mm		APVD	29MAR2007		PRODUCT SPEC								
						TOLERANCES UNLESS OTHERWISE SPECIFIED:			APPLICATION SPEC								
HV 100 HOUSING	LCP	BLACK	A	MATERIAL		SEE TABLE		WEIGHT		-		RESTRICTED TO					
DESCRIPTION	MATERIAL	FINISH/COLOR	SL.NO	SEE TABLE		SEE TABLE		CUSTOMER DRAWING		SCALE		SHEET		OF		REV	
										5:1		2		2		E	